

TECHNICAL DATA SHEET 2/5				
RIG	HT ANGLE SMT	E	R123.682.827	
REEL 100			Series : QMA	
PACKAGING Standard Unit 100 'W' option		SPECIFICATION		
ELECTRICAL CHARACTERISTICS			ENVIRONMENTAL	
Impedance Frequency VSWR Insertion loss RF leakage Voltage rating	0 - 6 1.05* + 0,0000 0.05 - (80**	Ω GHz x F(GHz) Maxi √F(GHz) dB Maxi - F(GHz)) dB Maxi Veff Maxi	Operating temper Hermetic seal Panel leakage	rature -40/+105 ° C NA Atm.cm3/s NA
	electric withstanding voltage 1000 Veff mini		OTHER CHARACTERISTICS	
MECHANICAL CHARACTERISTICS			Assembly instruction Others : *VSWR: up to 3GHz; 3-6GHz, 1.1 Max **RF leakage:Interf. only:3 <f<6ghz:>70dB</f<6ghz:>	
Center contact retenti Axial force – Matin Axial force – Oppos Torque	g end 27 site end 27	N mini N mini N.cm mini		
Recommended torque Mating Panel nut	NA	N.cm N.cm		
Mating life Weight	100 5,9500	Cycles mini g		
Issue: 1123 M In the effort to improve our products, we reserve the right to make changes judged to be RADIALLIS necessary.				

TECHNICAL DATA SHEET

RIGHT ANGLE SMT RECEPTACLE

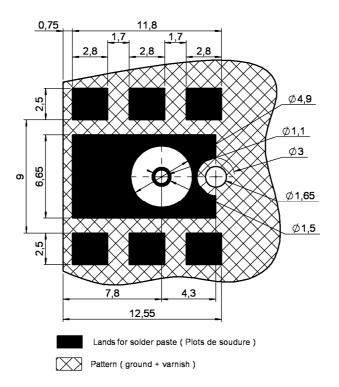
REEL 100

Series : QMA

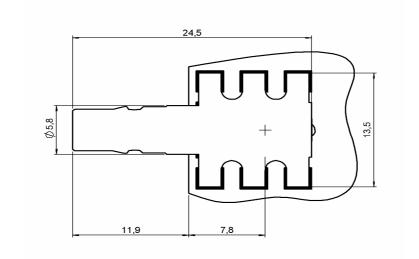
R123.682.827

QMA SERIE - INFORMATIONS

COPLANAR LINE : Pattern and signal are on the same side. Thickness of PCB = 0.063 (1.6mm). The material of PCB is the epoxy resin of glass fabrics bacs (Er = 4.8). The solder resist should be printed except for the land pattern on the PCB.



SHADOW OF QUICLOCK RECEPTACLE FOR VIDEO CAMERA





TECHNICAL DATA SHEET

RIGHT ANGLE SMT RECEPTACLE

REEL 100

4/5 **R123.682.827** Series : **QMA**

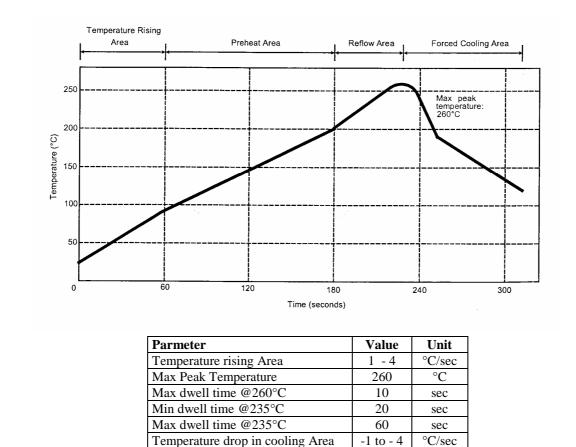
SOLDER PROCEDURE

 Deposit solder paste 'Sn95 Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.

We advise a thickness of 150 microns (5.850 microinch). Verify that the edges of the zone are clean.

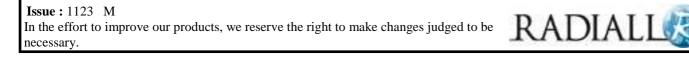
- 2. Placement of the receptacle on the mounting zone with an automatic 'pick and place' machine. Video camera is preferred to check the positioning of the component (See page 3). Adhesive agents are forbidden on the receptacle.
- Soldering by infra-red reflow.
 We give under, the typical profile to use.
- 4. Cleaning of the printed circuits board.
- 5. Checking of solder joints and position of the components by visual inspection.

TEMPERATURE PROFIL



420

sec



Max dwell time above 100°C

